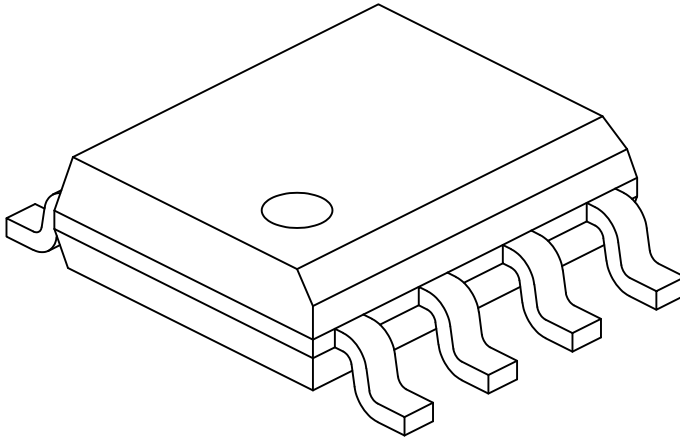


8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		1.27 BSC		
Overall Height	A	–	–		1.75
Molded Package Thickness	A2	1.25	–		–
Standoff §	A1	0.10	–		0.25
Overall Width	E		6.00 BSC		
Molded Package Width	E1		3.90 BSC		
Overall Length	D		4.90 BSC		
Chamfer (Optional)	h	0.25	–		0.50
Foot Length	L	0.40	–		1.27
Footprint	L1		1.04 REF		
Lead Thickness	c	0.17	–		0.25
Lead Width	b	0.31	–		0.51
Lead Bend Radius	R	0.07	–		–
Lead Bend Radius	R1	0.07	–		–
Foot Angle	θ	0°	–		8°
Mold Draft Angle	θ1	5°	–		15°
Lead Angle	θ2	0°	–		–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

5. Datums A & B to be determined at Datum H.